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FAIRCHILD SEMICONDUCTOR®

February 2008

74VHCT08A
Quad 2-Input AND Gate

Features

- High speed: t_{PD} = 5.0ns (typ.) at T_A = 25°C
- High noise immunity: V_{IH} = 2.0V, V_{IL} = 0.8V
- Power down protection is provided on all inputs and outputs
- Low noise: V_{OLP} = 0.8V (max.)
- Low power dissipation: I_{CC} = 2μA (max.) @ T_A = 25°C
- Pin and function compatible with 74HCT08

General Description

The VHCT08A is an advanced high speed CMOS 2 Input AND Gate fabricated with silicon gate CMOS technology. It achieves the high-speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

The internal circuit is composed of 4 stages including buffer output, which provide high noise immunity and stable output.

Protection circuits ensure that 0V to 7V can be applied to the input pins without regard to the supply voltage and to the output pins with V_{CC} = 0V. These circuits prevent device destruction due to mismatched supply and input/output voltages. This device can be used to interface 3V to 5V systems and two supply systems such as battery backup.

Ordering Information

Order Number	Package Number	Package Description
74VHCT08AM	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74VHCT08ASJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74VHCT08AMTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74HCT08AN	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

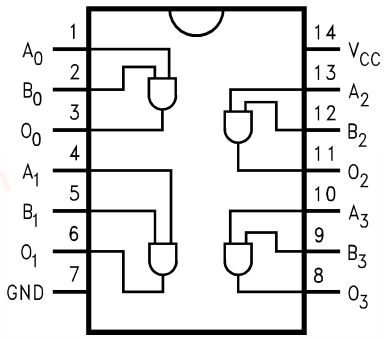
Device also available in Tape and Reel. Specify by appending suffix letter “X” to the ordering number.

All packages are lead free per JEDEC: J-STD-020B standard.

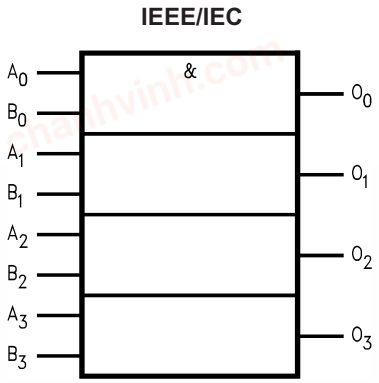
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Connection Diagram



Logic Symbol



Pin Description

Pin Names	Description
A_n, B_n	Inputs
O_n	Outputs

Truth Table

A	B	O
L	L	L
L	H	L
H	L	L
H	H	H

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Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	–0.5V to +7.0V
V_{IN}	DC Input Voltage	–0.5V to +7.0V
V_{OUT}	DC Output Voltage HIGH or LOW state, I_{OUT} absolute maximum rating must be observed	–0.5V to V_{CC} + 0.5V
	V_{CC} = 0V	–0.5V to +7.0V
I_{IK}	Input Diode Current	–20mA
I_{OK}	Output Diode Current, V_{OUT} < GND, V_{OUT} > V_{CC} (Outputs Active)	±20mA
I_{OUT}	DC Output Current	±25mA
I_{CC}	DC V_{CC} / GND Current	±50mA
T_{STG}	Storage Temperature	–65°C to +150°C
T_L	Lead Temperature (Soldering, 10 seconds)	260°C

Recommended Operating Conditions(1)

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	4.5V to 5.5V
V_{IN}	Input Voltage	0V to +5.5V
V_{OUT}	Output Voltage HIGH or LOW state, I_{OUT} absolute maximum rating must be observed	0V to V_{CC}
	V_{CC} = 0V	0V to +5.5V
T_{OPR}	Operating Temperature	–40°C to +85°C
t_r, t_f	Input Rise and Fall Time, V_{CC} = 5.0V ± 0.5V	0ns/V ~ 20ns/V

Note:

1. Unused inputs must be held HIGH or LOW. They may not float.

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DC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)	Conditions		T_A = 25°C Min.	Typ.	Max.	T_A = –40°C to +85°C Min.	Max.	Units
V_{IH}	HIGH Level	4.5			2.0			2.0		V
	Input Voltage	5.5			2.0			2.0		
V_{IL}	LOW Level	4.5					0.8		0.8	V
	Input Voltage	5.5					0.8		0.8	
V_{OH}	HIGH Level	4.5	$V_{IN} = V_{IH}$ or V_{IL}	I_{OH} = –50µA	4.40	4.50		4.40		V
	Output Voltage			I_{OH} = –8mA	3.94			3.80		
V_{OL}	LOW Level Output Voltage	4.5	$V_{IN} = V_{IH}$ or V_{IL}	I_{OL} = 50µA		0.0	0.1		0.1	V
				I_{OL} = 8mA			0.36		0.44	
I_{IN}	Input Leakage Current	0–5.5	V_{IN} = 5.5V or GND				±0.1		±1.0	µA
I_{CC}	Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND				2.0		20.0	µA
I_{CCT}	Maximum I_{CC}/ Input	5.5	V_{IN} = 3.4V, Other Inputs = V_{CC} or GND				1.35		1.50	mA
I_{OFF}	Output Leakage Current (Power Down State)	0.0	V_{OUT} = 5.5V				0.5		5.0	µA

Noise Characteristics

Symbol	Parameter	V_{CC} (V)	Conditions	T_A = 25°C Typ.	Limits	Units
V_{OLP}[2]	Quiet Output Maximum Dynamic V_{OL}	5.0	C_L = 50pF	0.4	0.8	V
V_{OLV}[2]	Quiet Output Minimum Dynamic V_{OL}	5.0	C_L = 50pF	–0.4	–0.8	V
V_{IHD}[2]	Minimum HIGH Level Dynamic Input Voltage	5.0	C_L = 50pF		2.0	V
V_{ILD}[2]	Maximum LOW Level Dynamic Input Voltage	5.0	C_L = 50pF		0.8	V

Note:

2. Parameter guaranteed by design.

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AC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)	Conditions	T_A = 25°C			T_A = –40°C to +85°C		Units
				Min	Typ	Max	Min	Max	
t_{PLH}, t_{PHL}	Propagation Delay	5.0 ± 0.5	C_L = 15pF		5.0	6.9	1.0	8.0	ns
			C_L = 50pF		5.5	7.9	1.0	9.0	
C_{IN}	Input Capacitance		V_{CC} = Open		4	10		10	pF
C_{PD}	Power Dissipation Capacitance		(3)		18				pF

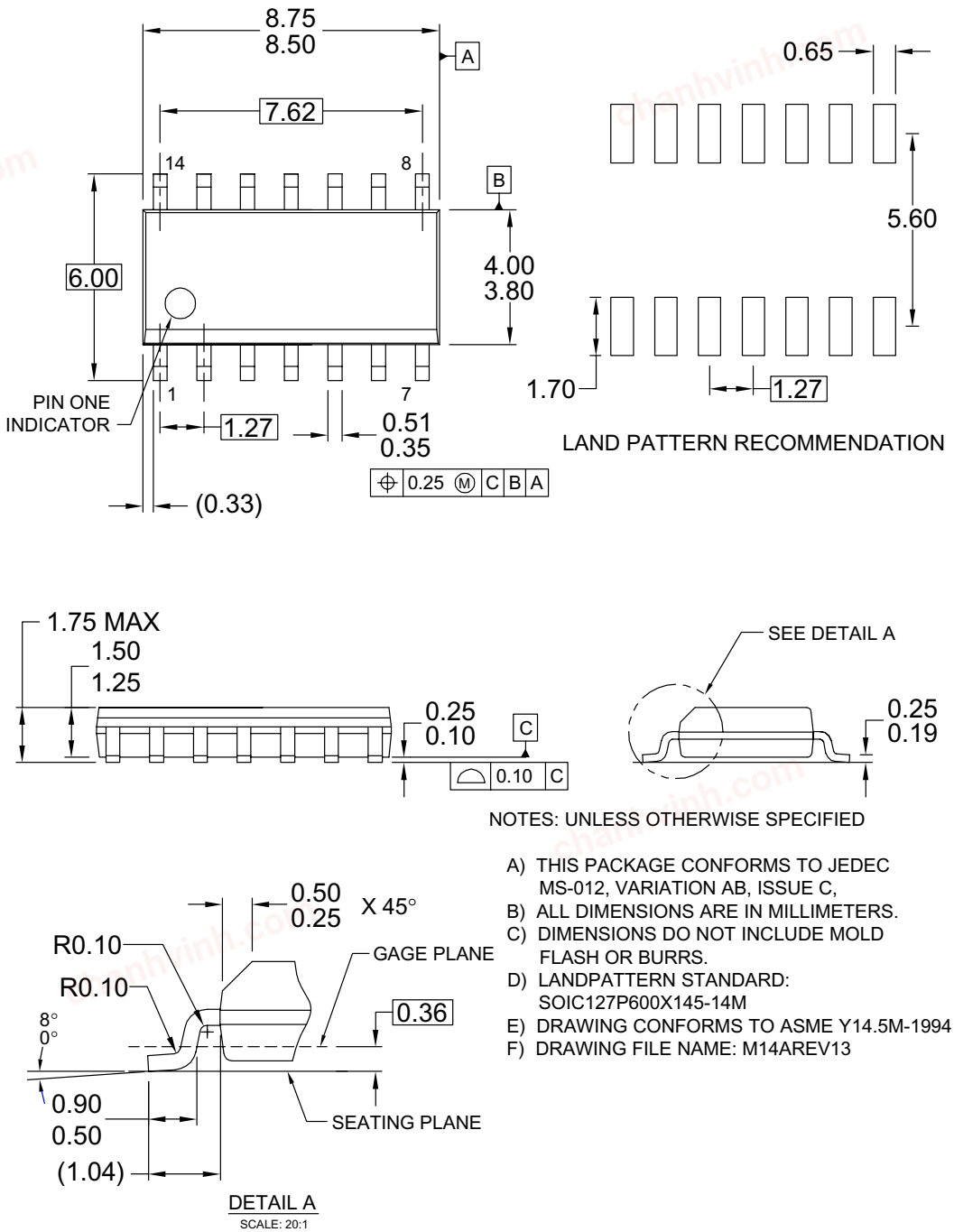
Note:

3. C_{PD} is defined as the value of the internal equivalent capacitance, which is calculated from the operating current consumption without load. Average operating current can be obtained from the equation:
   I_{CC} (opr.) = C_{PD} • V_{CC} • f_{IN} + I_{CC} / 4 (per gate)

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Physical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED

A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C,
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
D) LANDPATTERN STANDARD: SOIC127P600X145-14M
E) DRAWING CONFORMS TO ASME Y14.5M-1994
F) DRAWING FILE NAME: M14AREV13

Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow

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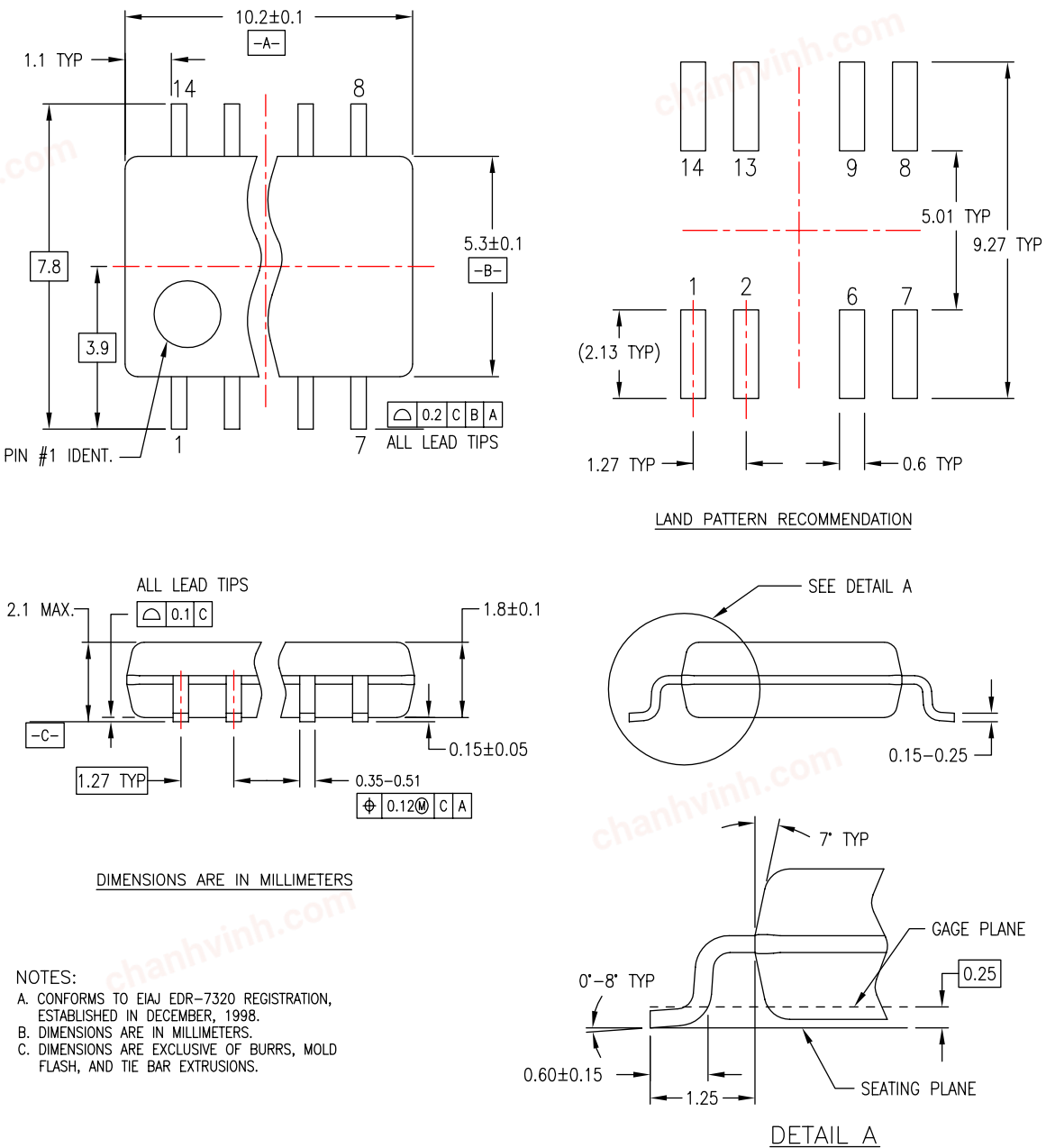
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Physical Dimensions (Continued)



NOTES:

A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
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C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M14DREVC

Figure 2. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

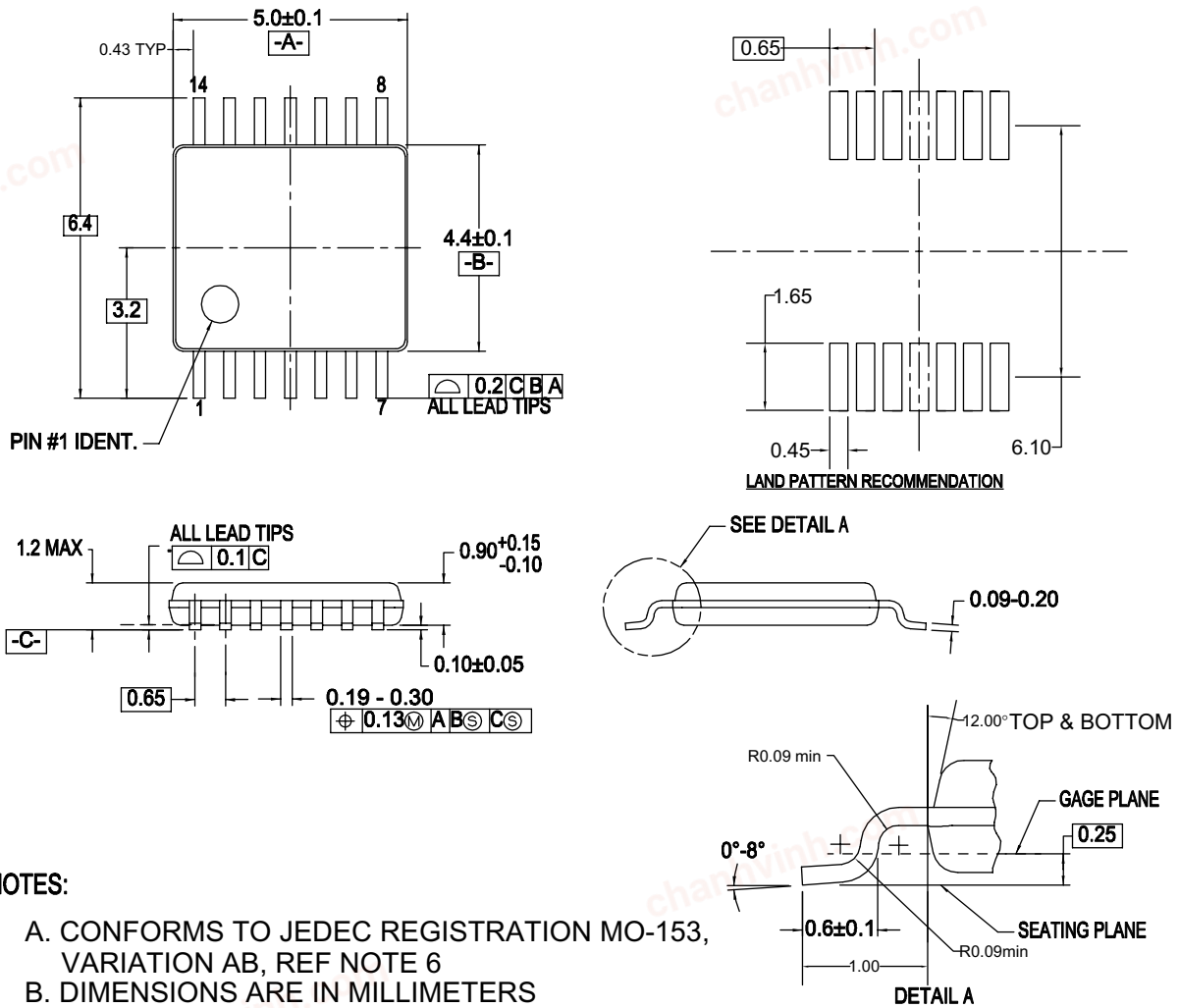
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Physical Dimensions (Continued)



NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6

B. DIMENSIONS ARE IN MILLIMETERS

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS

D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982

E. LANDPATTERN STANDARD: SOP65P640X110-14M

F. DRAWING FILE NAME: MTC14REV6

Figure 3. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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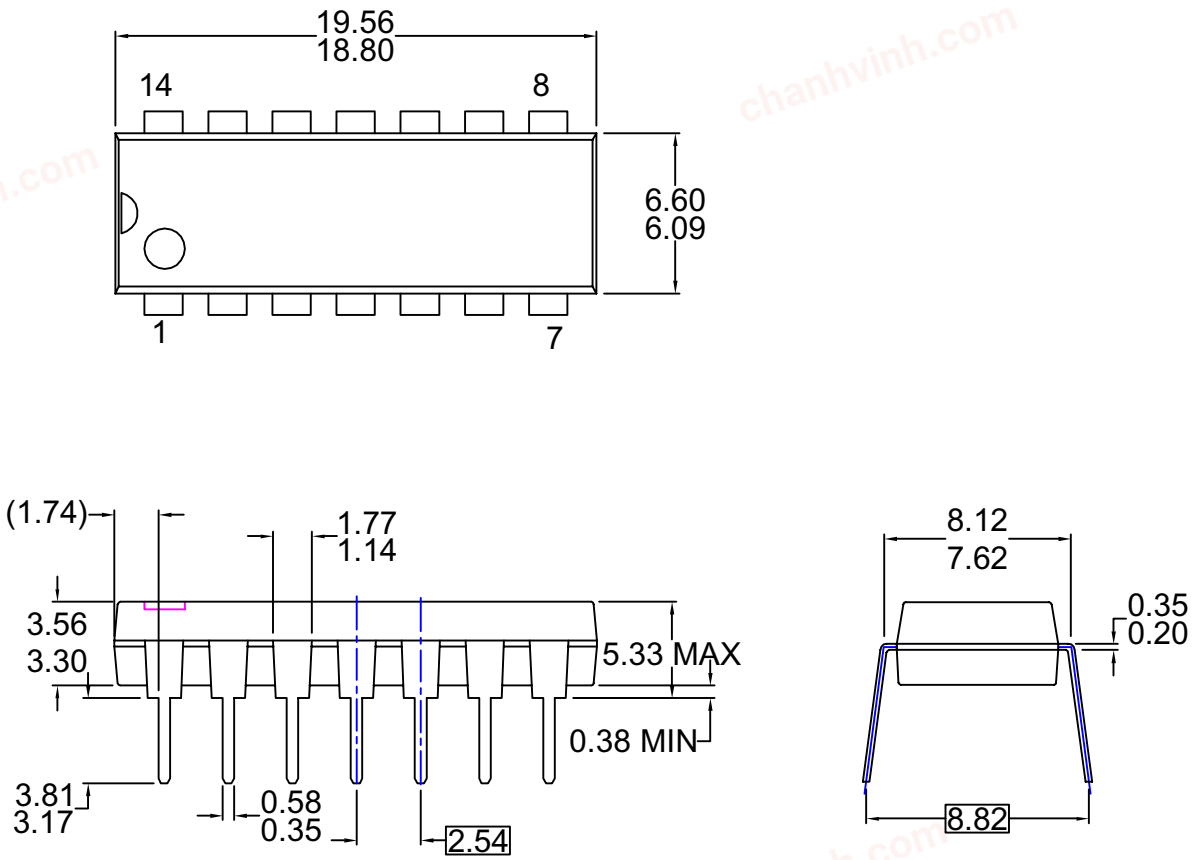
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Physical Dimensions (Continued)



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B) ALL DIMENSIONS ARE IN MILLIMETERS.
DIMENSIONS ARE EXCLUSIVE OF BURRS,

C) MOLD FLASH, AND TIE BAR EXTRUSIONS.

D) DIMENSIONS AND TOLERANCES PER
ASME Y14.5-1994

E) DRAWING FILE NAME: MKT-N14AREV7

Figure 4. 14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

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